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(71) Applicant (for all designated States except US): **MINUTA TECHNOLOGY CO. LTD.** [KR/KR]; San 56-1, Shilim-dong, Kwanak-gu, 151-742 Seoul (KR).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **KIM, Tae Wan**

[KR/KR]; #1-90, Sinkongduk-dong, Mapo-gu, 121-030 Seoul (KR). **YOO, Pil Jin** [KR/KR]; Samsung Apt. 113-1602, Songpa-2-dong, Songpa-gu, 138-172 Seoul (KR).

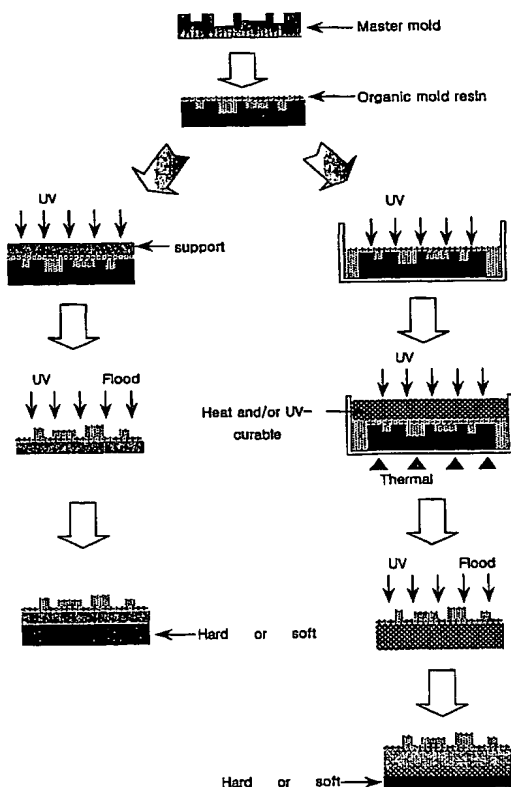
(74) Agents: **JANG, Seongku** et al.; 19th Fl., KEC Building, #275-7., Yangjae-dong, Seocho-ku, Seoul 137-130 (KR).

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(54) Title: RESIN COMPOSITION FOR MOLD USED IN FORMING MICROPATTERN, AND METHOD FOR FABRICATING ORGANIC MOLD THEREFROM



(57) Abstract: A resin composition for a mold used in forming micropatterns comprises (A) 40 to 90 parts by weight of an active energy curable urethane-based oligomer having a reactive group; (B) 10 to 60 parts by weight of a monomer reactive with the urethane-based oligomer; (C) 0.01 to 200 parts by weight of a silicone or fluorine containing compound, based on 100 parts of the sum of the components (A) and (B); and (D) 0.1 to 10 parts by weight of a photoinitiator, based on 100 parts of the sum of the components (A), (B) and (C). The inventive resin composition can be easily cured by the action of an active energy ray, and the organic mold fabricated therefrom is easily lifted off from a master without irreversible adhesion or generation of defects and have excellent dimensional and chemical stabilities.

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